



OCCASION

This publication has been made available to the public on the occasion of the 50th anniversary of the United Nations Industrial Development Organisation.

TOGETHER

for a sustainable future

DISCLAIMER

This document has been produced without formal United Nations editing. The designations employed and the presentation of the material in this document do not imply the expression of any opinion whatsoever on the part of the Secretariat of the United Nations Industrial Development Organization (UNIDO) concerning the legal status of any country, territory, city or area or of its authorities, or concerning the delimitation of its frontiers or boundaries, or its economic system or degree of development. Designations such as "developed", "industrialized" and "developing" are intended for statistical convenience and do not necessarily express a judgment about the stage reached by a particular country or area in the development process. Mention of firm names or commercial products does not constitute an endorsement by UNIDO.

FAIR USE POLICY

Any part of this publication may be quoted and referenced for educational and research purposes without additional permission from UNIDO. However, those who make use of quoting and referencing this publication are requested to follow the Fair Use Policy of giving due credit to UNIDO.

CONTACT

Please contact <u>publications@unido.org</u> for further information concerning UNIDO publications.

For more information about UNIDO, please visit us at www.unido.org

RESTRICTED

16557

September 1987 ENGLISH

BEIJING SPECIALITY GAS RESEARCH & DEVELOPMENT CENTRE

DP/CPR/85/005/11-03

CHINA

Conclusive Technical Report: Atomic Absorption Spectrography Analysis*

Prepared for the Government of the People's Republic of China by the United Nations Industrial Development Organization, acting as executing agency for the United Nations Development Programme

Based on the work of Juraj Bercik Expert in Atomic Absorption Spectrography Analysis

Backstopping officer: M. Derrough, Chemical Industries Branch

United Nations Industrial Development Organization Vienna

* This document has been reproduced without formal editing

Explanatary notes

Value of the local currency during the period of the mission : US \$ 1.00 = 3.70 Yuan Renmi /RMB/ RMB Yuan 1.00 = 0.27 US \$ -

Some technical abbreviations :

•

 AAS - Atomic Absorption Spectrophotometry FAAS - Flame Atomic Absorption Spectrophotometry GFAAS - Graphite Furnace Atomic Absorption Spectrophotometry MHS - Mercury Hydride System EDTA - Ethylenediaminetetraacetic acid DL - Detection Limit VLSI - Very Large Scale Integration OES - Optical Emission Spectroscopy ICP - Inductive Coupled Plasma DPP - Differential Pulse Polarography ESA - Electrochemical Stripping Analysis 	BSGRI	-	Beijing Specialty Gas Research Institute		
 FAAS - Flame Atomic Absorption Spectrophotometry GFAAS - Graphite Furnace Atomic Absorption Spectrophotometry MHS - Mercury Hydride System EDTA - Ethylenediaminetetraacetic acid DL - Detection Limit VLSI - Very Large Scale Integration OES - Optical Emission Spectroscopy ICP - Inductive Coupled Plasma DPP - Differential Pulse Polarography ESA - Electrochemical Stripping Analysis 	AAS	-	Atomic Absorption Spectrophotometry		
 GFAAS - Graphite Furnace Atomic Absorption Spectrophotometry MHS - Mercury Hydride System EDTA - Ethylenediaminetetraacetic acid DL - Detection Limit VLSI - Very Large Scale Integration OES - Optical Emission Spectroscopy ICP - Inductive Coupled Plasma DPP - Differential Pulse Polarography ESA - Electrochemical Stripping Analysis 	FAAS	-	Flame Atomic Absorption Spectrophotometry		
 MHS - Mercury Hydride System EDTA - Ethylenediaminetetraacetic acid DL - Detection Limit VLSI - Very Large Scale Integration OES - Optical Emission Spectroscopy ICP - Inductive Coupled Plasma DPP - Differential Pulse Polarography ESA - Electrochemical Stripping Analysis 	GFAAS	-	Graphite Furnace Atomic Absorption Spectrophotometry		
 EDTA - Ethylenediaminetetraacetic acid DL - Detection Limit VLSI - Very Large Scale Integration OES - Optical Emission Spectroscopy ICP - Inductive Coupled Plasma DPP - Differential Pulse Polarography ESA - Electrochemical Stripping Analysis 	MHS	-	Mercury Hydride System		
 DL - Detection Limit VLSI - Very Large Scale Integration OES - Optical Emission Spectroscopy ICP - Inductive Coupled Plasma DPP - Differential Pulse Polarography ESA - Electrochemical Stripping Analysis 	EDTA	-	Ethylenediaminetetraacetic acid		
 VLSI - Very Large Scale Integration OES - Optical Emission Spectroscopy ICP - Inductive Coupled Plasma DPP - Differential Pulse Polarography ESA - Electrochemical Stripping Analysis 	DL	-	Detection Limit		
 OES - Optical Emission Spectroscopy ICP - Inductive Coupled Plasma DPP - Differential Pulse Polarography ESA - Electrochemical Stripping Analysis 	VLSI	-	Very Large Scale Integration		
 ICP - Inductive Coupled Plasma DPP - Differential Pulse Polarography ESA - Electrochemical Stripping Analysis 	OES	-	Optical Emission Spectroscopy		
DPP - Differential Pulse Polarography ESA - Electrochemical Stripping Analysis	ICP		Inductive Coupled Plasma		
ESA - Electrochemical Stripping Analysis	DPP	-	Differential Pulse Polarography		
	ESA	-	Electrochemical Stripping Analysis		

Abstract

Project: Beijing Specialty Gases Research and Developing Centers, Atomic Absorption Spectrography Analysis DP/CPR/85/005/11-03/

Government Implementing Agency : Bureau of Chemical Industry of Beijing Municipal Government

Executing Agency : UNIDO

Name of expert : Juraj Berčík

Duty Station : Beijing, BSGRI, Dajiaoting, Chaoyang District, Peoples Republik of China

Duration : 16 days, August 1987

Expert was fielded on the project for the branch f Atomic Absorption Spectrophotometry. His main duty and task was to develop the capabilities of BSGRI personnel to set up, operate and utilize the atomic absorption spectrophotometry apparatus for ultratrace metal analysis /ppb levels/ in electronic grade high purity gases and dopant materials used for semiconductor manufacturing. Some sampling systems for separation, collection and enrichment of gas-borne particles were proposed.

Lectures about AAS, Selection and optimisation of AAS, Operating conditions, Advanced analytical methods for trace analysis, Sampling and collecting of gas-borne particles, Problems in ultratrace analysis and Advanced analytical instrument in gas analysis were made.

<u>Contents</u>

٠

-

-

Fynlanatary notes	2		
Abotmoot			
Recommendations			
Possibilies and utilisation of AAD in trace and	7		
ultratrace analysis in Bound			
1.1 BSGRI-Analytical Department Organization and	7		
Program	i		
2.2 Atomic Absorption Spectroscopy in Trace and	•		
Ultratrace Analysis	9		
2. Determination of Trace Metal Impurities in			
Electronic Grade High Purity Gases	9		
2.1 Electronic Gases and Dopant Materials Used			
for Semiconductor Manufacturing	9		
2.2 The Problem of Sampling and Collecting of Gas	;		
Borne Particles for Trace Metal Analysis	11		
2.2.1 Purity and Efficiency of the Filtering			
and Trapping Medium	12		
2.2.2 Low Background Contamination	12		
2.2.3 Sampling Volume/Time	13		
2.2.4 Dissolution of Solids on Filters or in			
Trapping Medium	13		
3 Separation and Collection of Particles			
by Solvent Wash	13		
3] Nitric Acid Wash	13		
2.2 Woton Wash	13		
J.2 Have wash			
4. Froblem of Direct Decommendation of Car Demps Bontialos without Separation and			
porne farticles without Deparation and	15		
Collecting	±/		

Annex 1 - 8

Introduction

The essential needs for chemical raw materials in ultrahigh purity states have been well established in the electronics industry. Exceptionally pure gases and volatile reagents have become essential raw materials for device fabrication technology. Their availability has been critical to production of epitaxial layers of device quality and to the succesful functioning of fabricated devices. Gaseous chemicals are key starting materials for device fabrication by chemical vapour deposition, metal organic chemical vapour deposition, liquid phase epitaxy and vapour phase epitaxy. Other volatile chemicals are used as carrier gases, vapour transport agents, dopants and for atmospheric control during semiconductor processing.

The aim and the purpose of the project /part 11.03/ was : 1. To establish the capability to measure ppb levels of trace metals in electronic grade high purity gases at BSGRI.

2. To obtain analytical accuracy in the aforementioned which is equivalent to that of the most advanced level in the world.

The main duty of the Job description and objective was to develop the capabilities of BSGRI personnel to set-up, operate and utilize the atomic absorption apparatus as follows : 1. Introduce a sampling system for the measurement of trace metals in gases recognizing the problems associated with flam-

mable, explosive and toxic compounds.

- 2. Introduce the techniques for the measurement of prm trace metals using flame AAS and flameless AAS for ppb levels of trace metals in gases.
- 3. Introduce the techniques to separate the trace metals from the major metals in a matrice.

The project started in the year 1986 and now is lasting one year. During this period there were two UNIDO experts working on the project :

Willard L. Ent, Chief Technical Adviser

Juraj Berčík, expert in Atomic Absorption Spectrography Activities program prepared by BSGR1 on the bases of Job Description is in annexe 1.

Recommendations

- In order to complete the establishment of research centers it is recommendet to buy the following advanced instruments :
 a. Emission spectrometer /ICP System/
 - b/ Particles counter of the medium
 - c/ Ion Chromatograph for determination of trace anions
 /ppb levels/
 - d/ Differential pulse polarograph including stripping
 analysis /DPP, ESA/
 - 2. To enable short-term and long-term fellowship training and study tours for operators in the field of trace analysis especially in the field of their application in trace gas analysis

1.1 BSGRI - ANALYTICAL DEPARTMENT ORGANIZATION AND PROGRAM

BSGRI is headed by Director Chen Jinming who is the head of the whole project. Based on the project targets, the BSGRI will establish the following research centres :

- 1. Analysis and Inspection Centre for Specialty Gases
- 2. The Secondary Mass Transfer Centre of National Standards
- 3. Safety and Protection Supervising Centre for Specialty Gases.

The electronic industry requires high purity electronic gases with extremely low metal content, hence there is requirement of metal impurity analysis at ultratrace levels /ppm, ppb and below/.

BSCRI - Analytical Department has the following analytical sections :

Section of Chromatography Section of Gas Chromatography GC/MS Section of Spectroscopy

Laboratory for trace element handling /Clean Room/ is simultaneously laboratory for atomic absorption spectrophotometry. From the point of view of contamination this is of course not the best solution. Laboratory is situated on the first floor in a new modern building. Clean room - laboratory has the vertical laminar airflow and about the US Federal Standard 209 B is classified as Class 100. The class number is the maximum allowable number of particles larger than 0.5 µm and smaller than 5 µm per cubic foot of air /about 28 liters/.

Laboratory is equipped with a new modern atomic absorption spectrophotometer Perkin-Elmer Model 3030 B manufactured in U.S.A. It is a doublebeam system, computer controlled with flame and flameless graphite tube atomiser and mercury hydride system. The instrument was installed and adjusted, but for practical application has not yet been utilized. Mastering these high level techniques requires of course more time, especially in the case of utilising them in ultra trace analysis.

The head of the Section of AAS is Madam Chen Zhi Fen who studied at the Beijing University and finished her study in the year 1963. Three other workers are :

- Assistant Engineer Li Shang, who studied physical chemistry at the Lanzhou University and finished his study in the year 1984.
- Assistant Engineer Liu Qing Chin, who studied physical chemistry at the Nankai University and finished his study in the year 1986.
- 3. Miss Fan Jin Wen, who studied analytical chemistry at the Chemical Institute of Technology in Beijing and finished her study in the year 1983.

On the photograph /from left to right/ there are : Ms Chen Zhi Fen, Mr Berčík /expert/, Mr Guc Bing Chen /professor and translater/,Ms Fan Jin Wen, Mr Li Shang and Mr Liu Qing Chin.



1. 2 ATOMIC ABSORPTION SPECTROSCOPY IN TRACE AND ULTRATRACE ANALYSIS

, Atomic absorption spectroscopy is one of the accepted techniques for metal analysis in the analytical laboratory. Several methods of metal atom vaporization are used in atomic spectroscopy with graphite furnace, flame atomization and mercury hydride system being three of the most widely used. The GFAAS technique provides minimum detection levels of subopb, while the flame atomization method is in the low ppm range. Although advances have been made in the GFAAS and FAAS techniques, some problems and difficulties can still be encountered, such as sample matrix related problem, gas-borne particle analysis problem/normally the sample in GFAAS can be introduced into the graphite hollow tube furnace only as a liquid or as a solid/.

The means whereby the utilization of atomic abosrption apparatus were reached were mainly through lecturing and discussing. The curriculum of lectures is given in annexes 2 - 8.

2. DETERMINATION OF TRACE METAL IMPURITIES IN ELECTRONIC GRADE HIGH PURITY GASES

There are a large number of specialty gases /about 35/ and for simplification they are usually categorized by chemical functionality and reactivity. The six specialty gas categories include silicon - precursor gases, dopants. plasma etchants, reactant gases, atmospheric /purge cylinder gases, as well as a final category designated "other" specialty gases.

<u>Silicon-precursor gases</u> such as silane and dichlorsilane are used in epitaxial and chemical vapor deposition processes to deposit layers of silicon, or silicon compounds /i. e. silicon dioxide, silicon nitride/ onto silicon substrates. <u>Dopants</u> like arsine, phosphine and diborane are used as a source of controllable impurities within semiconductor devices to modify local electrical properties of the medium, or to alter the characteristics of films.

<u>Plasma etchants</u> encompass a wide variety of halocarbon and fluorine-based gases, but carbon tetrafluoride is probably the most commonly used plasma etch gas.

<u>Reactant gases</u> include ammonia and hydrogen chloride /HCl/ Ammonia is used as a source of nitrogen in the production of silicon nitride layers in chemical vapour despsition. HCl is used to polish and etch wafers prior deposition steps by removing defects on the wafer surface due to mechanical polishing and handling of the wafer.

<u>Atmospheric/purge cylinder gases</u> - nitrogen and other atmospheric gases /including helium/ appear in this category. These gases are primarily used for purging certain processing systems and equipment.

"Other" specialty gases - tungsten hexafluoride is one example of this category. It is used as a source of tungsten for the deposition of tungsten silicide, which is used as an alternative interconnect material in VLSI devices.

The review of the most toxic hazardous and reactive gases is in the table 1 /Annex 8/. These gases are used for chemical vapour deposition, for ion implanting, doping, epitaxy and etching. The impurities which should be controlled are in the right of the table.

These gases require special sample handling techniques to prevent synamic changes in composition due to reactivity with atmospheric moisture, air, or because they are corrosive or extremly poisonous.

Specific procedures must be developed for the analysis of ammonia, arsine, phosphine and silane. Individual instrumentation adm safe handling systems need to be dedicated solely to each gas. Development of procedures for the convenient and reliable characterization of these reagents are much needed and would be noteworthy analytical contributions.

Due to extreme toxicity or other hazards, the working atmosphere must also be controlled to prevent intolerable levels of arsine, phosphine and the silenes.Extraordinarily sensitive techniques are required for determining the presence of these gases at the ppb level in the work space atmospheres of semiconductor processing facilities.

Contamination

All these high purity gases are primarily contaminated during storage, transportation and metering. Metal impurities are of particular importance due to their potential electrical activity in the forbidden band. Many of the components of the delivery system can generate particulates which may be many times the level of that in the filter effluent stream. Some of the causes of particulate contamination are walls of the piping system and gas cylinders, changing in the pipeline velocity, vibration of piping system, sampling valve, leaks and any mechanical device in the piping system. Hence gas borne impurity particles analysis at ultratrace levels is important for electronic gas purity validation.

2. 2 THE PROBLEM OF SAMPLING AND COLLECTING OF GAS-BORNE PARTICELS FOR TRACE METAL ANALYSIS

The metal impurities concentrations in high purity gases for microelectronics are on the level lower than 10^{-5} mass percent /e.g. 15 ng/l in a 10 Vol % phosphine mix/. Analysis of such materials requires a reproducible method of sampling and collecting /seperation and concentration/ of particulates from the matrix. The sizes of such particulates are between 0.01 to 2 μ m or more and the smaller the particulates the greater the stability and lifetime of aerosol.

Sampling system for gas-borne particels generally consist of thee parts:

- a means of cellecting a gas sample
- a device to trap the particles and
- a means of measuring the amount of gas sampled.

The technique for collecting air-borne or gas-borne particles are based on one of the following principles:filtration, impaction, sedimentation, centrifugation, thermal precipitation, electrostatic precipitation and solvent wash.

Filtr tion and impaction are the most frequently used methods. The succes of separation and collection of gas-borne

- 11 -

particles depands on: a/ purity and efficiency of the filtering or trapping medium; b/ low background contamination; c/ reasonable volume sampling; d/ sensitivity of the used cnalytical method.

2. 2. 1 PURITY NAD EFFICIENCY OF THE FILTERING OR TRAPPING MEDIUM

Filtration assembly consist of a sampling head filter and the pump. There are several types of filters: Depth filters. membrane filters, filtration through graphite. While such sampling and collecting media are widely used, the problem originates from the fact, that the filter materials exhibit significant residual blanks for a number trace elements of interest. The existence of these blanks does not present a serious problem if long term, high volume sampling is used to collect sufficient sample to render the blank contribution negligible / 20 - 50 L/. However in relatively clean gases the use of such collection materials may necesitate inordinately long sampling periods. To achieve consistent and low background levels it is necessary to reduce contributions due to solvents, glassware, handling etc. and the filters material must be precleaned before use. Many problems concerning trace and ultratrace analysis were discussed and lectured /annex 6/.

2. 2. 2 LOW BACKGROUND CONTAMINATION

The first step in contamination control is "clean" sample preparation. Due to reactive and hygroscopic nature of some dopants, direct analysis without handling, transfer and sample preparation would be the preferred approach to avoid potential contamination from surfaces or reagents. Unfortunately most analytical techniques necessitate sample handling and preparation and a wide range of precautions are required clean room, glove box with an atmosphere of argon or nitrogen containing less than 1 ppm of water and oxygen). 2. 2. 3 SAMPLING VOLUME/TIME

The minimum sample volume required to obtain a reasonable AAS analytical signal can be easily calculated using the characteristic concentration of the element.

2. 2. 4 DISSOLUTION OF SOLIDS ON FILTERS OR IN TRAPPING MEDIUM

The particulate matter collected on the filter has to be dissolved for analysis. Wet or dry ashing procedures are used. Although numerous procedural variations for this operation exist, some elements often cannot be subjected to dry ashing due to their high volability. For wet-ashing procedure depending on the element analyzed and the AA techniques used, various acid concentrations and mixtures may be utilized.

3. SEPERATION AND COLLECTION OF PARTICLES BY SOLVENT WASH

3. 1 NITRIC ACID WASH

Kuzmin /Elektronnaja technika, Ser. 6, 94 /1974/; Ž. Analit. Chimii, 24, 429 /1969// proposed a method in which the elements Cu, Fe, Co, Pb, Ni, Bi in phosphine /PH₃/ and arsine /AsH₃/ are separated by nitric acid wash /6 vitreous silica absorber with 25 ml HNO₃/. Active components arsine and phosphorus are oxidised to arsenic /H₃AsO₄/ and phosphoric /H₃PO₄/ acids and metal impurities are dissolved. The resulting H₃PO₄ - HNO₃ solutions were connected and at $= 100^{\circ}$ C evaporated in order to prevent the building of disturbing higher phosphoric acids. There is, of course, the danger of loss of some elements especially of Pb, Mn, Sb, Ti, and Sn. Contamination during this acid digestion and evaporation may realt in introduction of systematic errors due to the high blank.

3. 2 WATER WASH

Kochler /Chem. Techn. 37, 103 /1985// proposed a method in which the elements are separated by water wash without reaction of the matrices PH_3 , AsH_3 and SiH_4 . For trapping the particles serves a device composed from six ground inverted decomposable fused silica scrubber /to prevent contamination is the outer ground joint socked about the inner ground joint cone/ with inlet capillary of 0,5 mm diameter. Every scrubber was with 25 ml of high purity water filled. In the case of trapping the boron addition of 330 ug of mannitol was made. The pH 10 of the solution was adjusted with ammonium hydroxide and oxygen, by passing of high purity hydrogen, was removed.

In the case of monosilan undecomposable scrubbers placed in a clean hood with inert gas atmosphere were used. Alkali ions must be excluded.

Before analysis the sample bottles /cylinders/ in order to reach homogenity were 10 minutes rolled and then the gas /30 to 60 1/ was through a special gas reducing valve sampled at a rate 25 1/h: In the end the apparatus was rinsed out with hydrogen. Washing solutions were then collected and before spectrometric analysel concentrated by evaporating. Evaporation in closed chambers purged with clean air continues to be the preferred concentration technique. Contamination from heating apparatus and the evaporation vessel can be reduced and effectively controlled.

The delivering of PH_3 and AsH_3 can be done with a connected absorptive apparatus with HNO_3 ; SiH_4 is air burned.

If 50 l of gas are used the relative detection limit by an OES collector technique amounts to 10 ng/l. The average error of determination of a single value amounts to between 10 to 80 %.

The success of separation and collection of gas-born particles for trace metal analysis depands on these factors: first - purity and efficiency of the filtering or trapping medium

second - low background contamination enables low volume sampling in the case of using a sensitive analytical method for accurate determination.



MICROCOPY RESOLUTION TEST CHART NATIONAL BUREAU OF STANDARDS STANDARD REFERENCE MATERIAL 10104 (ANSLAND FO TEST CHART No. 2)

4. PROBLEM OF DIRECT DETERMINATION OF GAS BORNE PARTICLES WITHOUT SEPARATION AND COLLECTING

Direct analysis in ultratrace region without handling and sample preparation should be the preferred approach to avoid potential contamination. Only GFAAS provides the possibility of analysis in this concentration region. Problem is how a gas sample, which is toxic and explosive, could be injected into the graphite tube furnace at the atomizing temper: ture.

5. CONCLUSION

Analysis of gas borne particles can be made:

- 1. by separating the solid particles by filtration through
 a membrane filter /cellulose, glass or plastic mate rial/
- 2. or through a porous graphite cup or cylinder .

In the former method the determinations are made by transferring the whole part of the filter into a suitable atomisation cell, whereas in the latter technique the graphite filter also serves as the atomization cell. Gas borne particulate matter can also be collected electrostatically in a graphite tube which is than transferred into the he ting circuit for atomisation.

- 3. by separating the solid particles by solvent wash and using the evaporation technique and the normal liquid technique for atomisation.
- 4. Direct analysis of gas borne particles is teoretically possible , but it needs more time for research.

Activities programm of expert in atomic absortion spectrophotometrie

- 21. 8. Arrivel in Beijing /4.00 p. m./ Project manager meets Mr. Berčik at Beijing International Airport
- 22. 8. Introducing with BSGRI Introducing with Perkin Elmer 3030 AAS
- 24. 8. Introducing the various analytical methods for measuring trace impurities /Annex 2/ Visiting UNDP resident office
- 25. 8. Lecture on advanced theory and operating technique of flame AAS and flamless AAS /Annex 3/
- 36. 8. Experiment Measuring ppb level metal by using flamless AAS and discussing
- 27. 8. Selection and optimisation of AAS operat ng conditions /Annex 4/
- 28. 8. Sampling system for the measurement of trace metals in flammable and toxic gases /Annex 5/.
- 29. 8. Go outing

六

- 31. 8. General problems in trace and ultratrace analysis /Annex 6/
 - 1. 9. Electroanalytical methods in trace analysis
 - 2. 9. Advanced analytical instruments in gas analysis /Annex 7/ Lecture for the whole institute. Departure from Beijing 21.30

Curriculum of lecture:

Introducing to various analytical methods for measuring trace impurities

1. Trace and ultratrace level

2. Sensitive techniques used in inorganic strace analysis

3. Metrological parameters of analytical methods

4. Atomic emission spectroscopy

5. Inductivity coupled plasma AES

6. FAAS and GFAAS

7. Spark source and ICP mass spectrometry

8. Neutron activation analysis

9. Substechiometric isotope dilution method

10. Differential pulse polarography

11. Stripping voltammetry

Curriculum of lecture:

ATOMIC ABSORPTION SPECTROPHOTOMETRY

- 1. Princip of AAS
- 2. Relation between atomic absorption and concentration
- 3. Atomization of sample
- 4. Comparison of FAAS and GFAAS
- 5. Methods to correct background absorption
- 6. \perp nstrumentation
- 7. The flame atomizer
- 8. Spray chamber assembly and the burner
- 9. Sample introduction
- 10. Electrothermal atomisation
- 11. Vapour generation techniques

Curriculum of lecture:

SELECTION AND OPTIMISATION OF AAS OPERATING CONDITIONS

- 1. Sensity and chara teristic concentration in AAS
- 2. Furnace operating conditions
- 3. Drying
- 4. Dry/Ash control
- 5. Atomisation
- 6. Preparation of atomise curve
- 7. Preparation of ashing curve
- 8. Tube cleaning
- 9. Interference effects in AAS
- 10. Matrix effects
- 11. Stable compound effects
- 12. Overcoming chemical interference effects

Curriculum of lecture:

THE PROBLEM OF COLLECTING GAS - BORNE PARTICLES FOR TRACE METAL ANALYSIS

- 1. Introduction
- 2. Sources of gas contamination
- 3. Size of particulates
- 4. Metal impurities concentrations in high purity gases
- 5. General scheme for inorganic trace analysis
- 6. Sampling system for gas-borne particles
- 7. Impactors
- 8. Filtration
- 9. Sampling volume/time
- 10. Calculating the minimum sample volume
- 11. Dissolution of solids on filters
- 12. Ashing of the filters

Curriculum of lecture:

GENERAL PROBLEMS IN TRACE AND ULTRATRACE ANALYSIS

- 1. Parameter which must be controlled in trace analysis
- 2. Contamination
- 3. Blank value
- 4. Detection limit
- 5. Control of contamination and loss
- 6. Airborne contamination
- 7. Clean rooms and clean hoods
- 8. Contamination and loss due to apparatus
- 9. Contamination due to reagents
- 10. Method of purification
- 11. Distillation and sub-boiling distillation
- 12. Isothermal distillation
- 13. Other sources of contamination and loss
- 14. Stability of standard solutions.

Curriculum of lecture:

ADVANCED ANALYTICAL INSTRUMENT IN GAS ANALYSIS

- 1. Purity monitoring
- 2. Bulk gases
- 3. Specialty gases
- 4. Purity specifications
- 5. Control of impurities in relatively chemically inert gases

.

.

- 6. Control of impurities in stable hydrocarbons
- 7. Control fo impurities in toxic hazardous reactive gases

CONTROL OF IMPURITIES IN TOXIC HAZARDOUS GASES

.

1 1 1

Reagent		Impurities Controlled
Ammonia	NH ₃	CO, H ₂ O, THC, H ₂ , O ₂ ,
Arsine	AsH3	CO, CO ₂ , H_2 , N_2 , O_2 , THC, Total Sulfur, H_2O , metals
Boron Trichloride	BC13	-
Boron Trifluoride	BF3	0 ₂ , N ₂ , SO ₂ , SiF ₄
Chlorine	C1_2	-
Dichlorsilane	Cl ₂ SiH ₂	SiCl ₄ , SiCl ₃ H, etc.,As,B,
		C, Fe, P, Si ₂ Cl _x O _y
Flurine	F ₂	-
Germane	GeH	AsH ₃ , PH ₃ , SiH ₄
Hydrogen Chloride	HCl	CO23, H2, N2, O2, inert gases
		THC, H ₂
Phosphine	PH ₃	$H_2, N_2, O_2, THC, AsH_3, CO_2,$
	-	H ₂ , H ₂ O
Silane	SiHA	$CO, CO_2, metals, HCl, H_2,$
	Ŧ	$Cl_{x}SiH_{4-x}, N_{2}, O_{2}, H_{2}O,$
		$\operatorname{Si}_{x}^{H} \operatorname{H}_{2x-2}^{H}$, $\operatorname{SiO}_{x}^{H} \operatorname{H}_{x}^{H}$

THC - Total Hydrocarbons as CH4